

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
18 January 2001 (18.01.2001)

PCT

(10) International Publication Number
WO 01/04963 A1

(51) International Patent Classification⁷: H01L 31/12, 33/00, H05B 33/00, H05K 5/02

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(21) International Application Number: PCT/SG99/00073

(22) International Filing Date: 9 July 1999 (09.07.1999)

(25) Filing Language: English

(26) Publication Language: English

(81) Designated States (*national*): AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZA, ZW.

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(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

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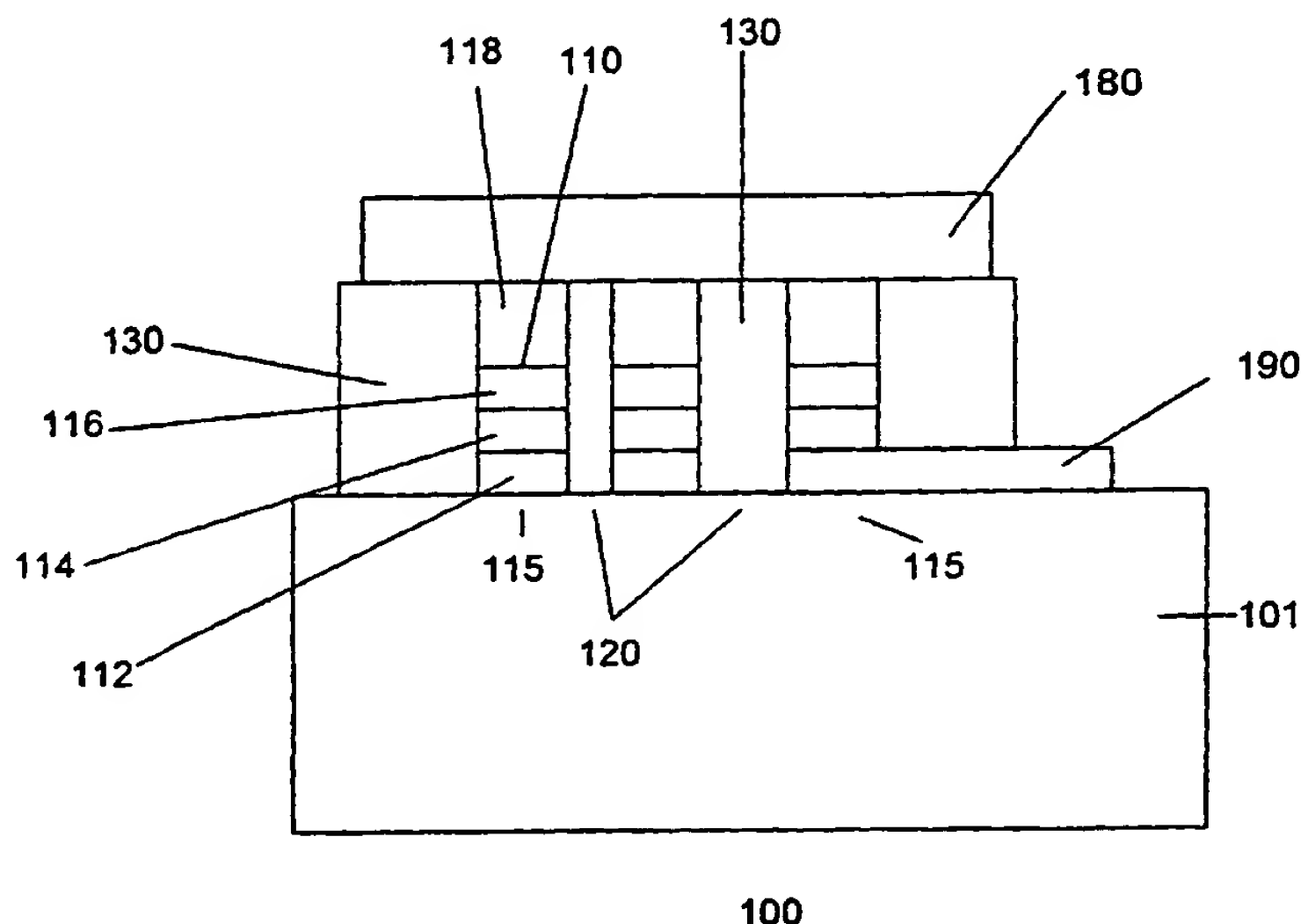
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Published:

— With international search report.

[Continued on next page]

(54) Title: ENCAPSULATION OF A DEVICE



(57) Abstract: An encapsulation for an electrical device (100) is disclosed. A cap support (130) is provided in the non-active regions (120) of the device (100) to prevent the package from contacting the active components (110) of the device due to mechanical stress induced in the package.